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Application No.: 10/564,470Docket No.: 2134-034**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently amended) Component for a circuit board, the component comprising a housing including at least one peg for engaging fitting into a hole in the circuit board; the peg having at least one detent lug which projects in the radial direction relative to the peg beyond the peg outer periphery; the detent lug being arranged on the peg such that the outer periphery of the peg is smaller in the region of the detent lug than the diameter of the hole in the circuit board; the outer periphery of the section of the peg protruding into the hole in the circuit board being such that between the outer periphery of the peg section and the inner wall of the hole in the circuit board, over at least a portion of the outer periphery, there is an intermediate space with capillarity for solder, such that solder situated on the surface of the circuit board during a soldering procedure penetrates by capillary action into the intermediate space and fills the intermediate space, filling it the periphery of the peg in the longitudinal direction over its entire portion located in the hole in the circuit board including at least one cut-out.

2. (Previously presented) Component according to claim 1, wherein the detent lug is arranged on the peg such that with the component placed fully on the circuit board, the detent lug is within the hole in the circuit board.

3. (Canceled)

4. (Currently amended) Component according to claim 2[[3]], wherein the hole in the circuit board is metallised.

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5. (Previously presented) Component according to claim 4, wherein the peg is made of plastics.

6. (Currently amended) Component according to claim 1, wherein the periphery of the peg in the longitudinal direction over the entire portion located whole section situated in the hole in the circuit board includes at least one cut-out.

7. (Previously presented) Component according to claim 1, wherein the hole in the circuit board is metallised.

8. (Previously presented) Component according to claim 1, wherein the peg is made of plastics.

9. (Previously presented) Method of inserting the component of claim 1 into the circuit board of claim 1, the method being performed by applying soldering paste on the circuit board around at least a portion of the periphery of the hole, placing the component into said circuit board with the peg in the hole in said circuit board, heating the solder around the hole such that the solder penetrates by capillary action into the intermediate space with the capillarity, and cooling the solder which has penetrated into the hole, such that the solder which has penetrated into the hole hardens.

10. (New) An electrical component arrangement comprising:

a circuit board having (a) a non-metallised surface and (b) a hole with a first wall, the hole being in the surface and the first wall being metallised;

a component having a peg fixedly located in the hole; the peg having a second wall spaced from and extending in the same direction as the metallised first wall, the metallised first wall and the second wall being spaced such that solder located on the non-metallised surface around and immediately beyond the metallised first wall, when

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heated to a liquid, can flow by capillary action into and fill the space between the metallised first wall and the second wall;

the space between the metallised first wall and the second wall being filled by the solder in solid form, the solder in solid form being supported in the space by an adhesion force to the metallised wall in a form-fitting manner to provide a form-fitting connection between the circuit board and the peg,

the peg having an end including a detent lug extending partially into the space between the first and second walls and held in place by the solder in solid form to provide a form-fit in the direction of the longitudinal axis of the first wall; the connections of the peg to the circuit board being such that the peg is firmly connected to the circuit board in all three spatial directions and the connection is able to absorb turning moments without the peg becoming loosened from the hole.

11. (New) The electrical component arrangement of claim 10 wherein the first metallised wall has circular cross-sections in planes at right angles to the longitudinal axes of the first and second walls and the peg has cross-sections at right angles to the longitudinal axes of the first and second walls that include (a) first and second spaced arcuate cut out portions that are concave with respect to the first wall and spaced from the first wall, and (b) a third arcuate portion having (i) opposite ends connected to end tips of the first and second arcuate portions and (ii) a shape geometrically similar to the shape of the first wall, the detent lug being diametrically opposite from the third arcuate portion.

12. (New) The electrical component arrangement of claim 11 wherein the peg cross-sections at right angles to the longitudinal axes of the first and second walls include a straight portion opposite to the third arcuate portion, the detent lug extending beyond the straight portion away from the third arcuate portion.

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13. (New) The electrical component of claim 12 wherein the surface is the bottom surface of the circuit board.

14. (New) The electrical component of claim 10 wherein the surface is the bottom surface of the circuit board.

15. (New) The electrical component of claim 10 wherein the peg is made of plastic.

16. (New) The method of claim 9 wherein the solder paste is applied to a bottom surface of the circuit board.

17. (New) The component of claim 1 wherein the intermediate space is in the form of a longitudinal recess in the peg.